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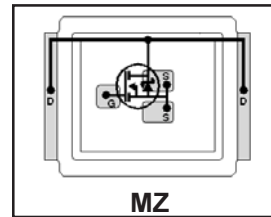
# IRF6674TRPbF

DirectFET™ Power MOSFET ②

Typical values (unless otherwise specified)

- RoHS Compliant ①
- Lead-Free (Qualified up to 260°C Reflow)
- Application Specific MOSFETs
- Ideal for High Performance Isolated Converter Primary Switch Socket
- Optimized for Synchronous Rectification
- Low Conduction Losses
- High Cdv/dt Immunity
- Dual Sided Cooling Compatible ①
- Compatible with existing Surface Mount Techniques ①

<b>V<sub>DSS</sub></b>	<b>V<sub>GS</sub></b>	<b>R<sub>DS(on)</sub></b>
60V max	±20V max	9.0mΩ @ 10V
<b>Q<sub>g tot</sub></b>	<b>Q<sub>gd</sub></b>	<b>V<sub>gs(th)</sub></b>
24nC	8.3nC	4.0V



Applicable DirectFET Outline and Substrate Outline (see p.7,8 for details)①

SH	SJ	SP	<b>MZ</b>	MN					
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## Description

The IRF6674PbF combines the latest HEXFET® Power MOSFET Silicon technology with the advanced DirectFET™ packaging to achieve the lowest on-state resistance in a package that has the footprint of an Micro8 and only 0.7 mm profile. The DirectFET package is compatible with existing layout geometries used in power applications, PCB assembly equipment and vapor phase, infra-red or convection soldering techniques, when application note AN-1035 is followed regarding the manufacturing methods and processes. The DirectFET package allows dual sided cooling to maximize thermal transfer in power systems, improving previous best thermal resistance by 80%.

The IRF6674PbF is optimized for primary side sockets in forward and push-pull isolated DC-DC topologies, for 48V and 36V-60V input voltage range systems. The reduced total losses in the device coupled with the high level of thermal performance enables high efficiency and low temperatures, which are key for system reliability improvements, and makes this device ideal for high performance isolated DC-DC converters.

## Absolute Maximum Ratings

	Parameter	Max.	Units
V <sub>DS</sub>	Drain-to-Source Voltage	60	V
V <sub>GS</sub>	Gate-to-Source Voltage	±20	
I <sub>D</sub> @ T <sub>A</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V ③	13.4	A
I <sub>D</sub> @ T <sub>A</sub> = 70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V ③	10.7	
I <sub>D</sub> @ T <sub>C</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V ④	67	
I <sub>DM</sub>	Pulsed Drain Current ⑤	134	
E <sub>AS</sub>	Single Pulse Avalanche Energy ⑥	98	mJ
I <sub>AS</sub>	Avalanche Current ⑥	13.4	A

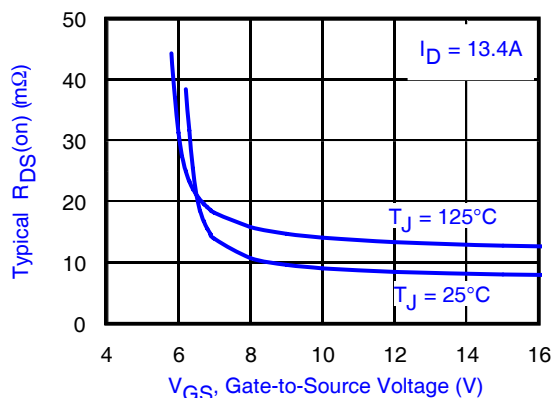


Fig 1. Typical On-Resistance vs. Gate Voltage

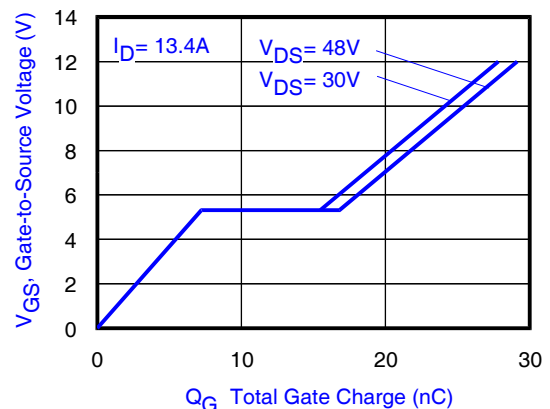


Fig 2. Typical Total Gate Charge vs. Gate-to-Source Voltage

Notes:

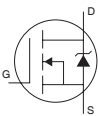
- ① Click on this section to link to the appropriate technical paper.
- ② Click on this section to link to the DirectFET Website.
- ③ Surface mounted on 1 in. square Cu board, steady state.

- ④ T<sub>C</sub> measured with thermocouple mounted to top (Drain) of part.
- ⑤ Repetitive rating; pulse width limited by max. junction temperature.
- ⑥ Starting T<sub>J</sub> = 25°C, L = 0.272mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 13.4A.

## Electrical Characteristic @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
B <sub>V</sub> DSS	Drain-to-Source Breakdown Voltage	60	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔB <sub>V</sub> DSS/ΔT <sub>J</sub>	Breakdown Voltage Temp. Coefficient	—	0.07	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance	—	9.0	11	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 13.4A ②
V <sub>GS(th)</sub>	Gate Threshold Voltage	3.0	4.0	4.9	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 100μA
ΔV <sub>GS(th)</sub> /ΔT <sub>J</sub>	Gate Threshold Voltage Coefficient	—	-11	—	mV/°C	
I <sub>DSS</sub>	Drain-to-Source Leakage Current	—	—	20	μA	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V
		—	—	250		V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	—	—	100	nA	V <sub>GS</sub> = 20V
	Gate-to-Source Reverse Leakage	—	—	-100		V <sub>GS</sub> = -20V
g <sub>fs</sub>	Forward Transconductance	16	—	—	S	V <sub>DS</sub> = 25V, I <sub>D</sub> = 13.4A
Q <sub>g</sub>	Total Gate Charge	—	24	36		
Q <sub>gs1</sub>	Pre-V <sub>th</sub> Gate-to-Source Charge	—	5.4	—		
Q <sub>gs2</sub>	Post-V <sub>th</sub> Gate-to-Source Charge	—	1.9	—		
Q <sub>gd</sub>	Gate-to-Drain Charge	—	8.3	12		
Q <sub>godr</sub>	Gate Charge Overdrive	—	8.4	—		
Q <sub>sw</sub>	Switch Charge (Q <sub>gs2</sub> + Q <sub>gd</sub> )	—	10.2	—		
Q <sub>oss</sub>	Output Charge	—	14	—	nC	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V
R <sub>G</sub>	Gate Resistance	—	1.0	—	Ω	
t <sub>d(on)</sub>	Turn-On Delay Time	—	7.0	—		
t <sub>r</sub>	Rise Time	—	12	—		
t <sub>d(off)</sub>	Turn-Off Delay Time	—	12	—	ns	V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V ② I <sub>D</sub> = 13.4A R <sub>G</sub> = 6.2 Ω
t <sub>f</sub>	Fall Time	—	8.7	—		
C <sub>iss</sub>	Input Capacitance	—	1350	—		
C <sub>oss</sub>	Output Capacitance	—	390	—	pF	V <sub>GS</sub> = 0V V <sub>DS</sub> = 25V
C <sub>rss</sub>	Reverse Transfer Capacitance	—	105	—		f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	1580	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 1.0V, f=1.0MHz
C <sub>oss</sub>	Output Capacitance	—	290	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 48V, f=1.0MHz

## Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode) T <sub>J</sub> = 25°C	—	—	67	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ⑤	—	—	134		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.3	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 13.4A, V <sub>GS</sub> = 0V ②
t <sub>rr</sub>	Reverse Recovery Time	—	32	48	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 13.4A, V <sub>DD</sub> = 50V
Q <sub>rr</sub>	Reverse Recovery Charge	—	36	54	nC	di/dt = 100A/μs ①

### Notes:

- ⑤ Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width ≤ 400μs; duty cycle ≤ 2%.

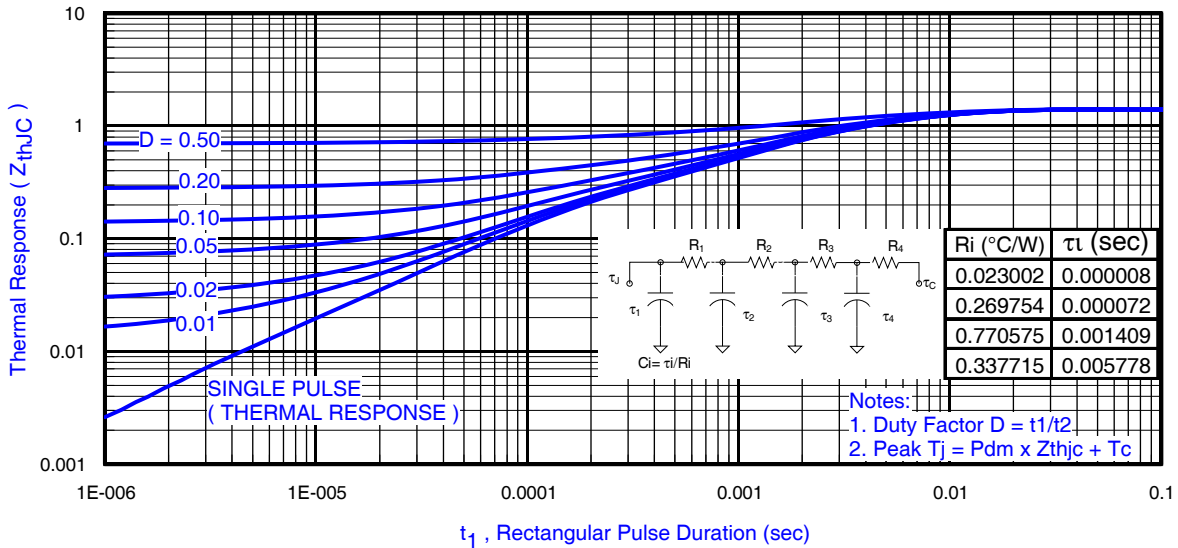


**Absolute Maximum Ratings**

	Parameter	Max.	Units
$P_D @ T_A = 25^\circ\text{C}$	Power Dissipation ③	3.6	W
$P_D @ T_A = 70^\circ\text{C}$	Power Dissipation ③	2.3	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation ④	89	
$T_P$	Peak Soldering Temperature	270	$^\circ\text{C}$
$T_J$	Operating Junction and	-40 to + 150	
$T_{STG}$	Storage Temperature Range		

**Thermal Resistance**

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③⑩	—	35	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction-to-Ambient ⑧⑩	12.5	—	
$R_{\theta JA}$	Junction-to-Ambient ⑨⑩	20	—	
$R_{\theta JC}$	Junction-to-Case ④⑩	—	1.4	
$R_{\theta J-PCB}$	Junction-to-PCB Mounted	1.0	—	



**Fig 3. Maximum Effective Transient Thermal Impedance, Junction-to-Case ①**

**Notes:**

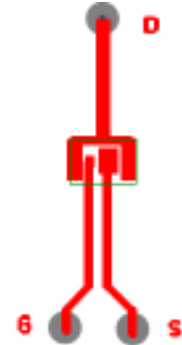
- ③ Surface mounted on 1 in. square Cu board, steady state.
- ④  $T_C$  measured with thermocouple incontact with top (Drain) of part.
- ⑧ Used double sided cooling, mounting pad with large heatsink.
- ⑨ Mounted on minimum footprint full size board with metalized back and with small clip heatsink.
- ⑩  $R_{\theta}$  is measured at  $T_J$  of approximately  $90^\circ\text{C}$ .



③ Surface mounted on 1 in. square Cu board (still air).



⑨ Mounted on minimum footprint full size board with metalized back and with small clip heatsink. (still air)



# IRF6674TRPbF

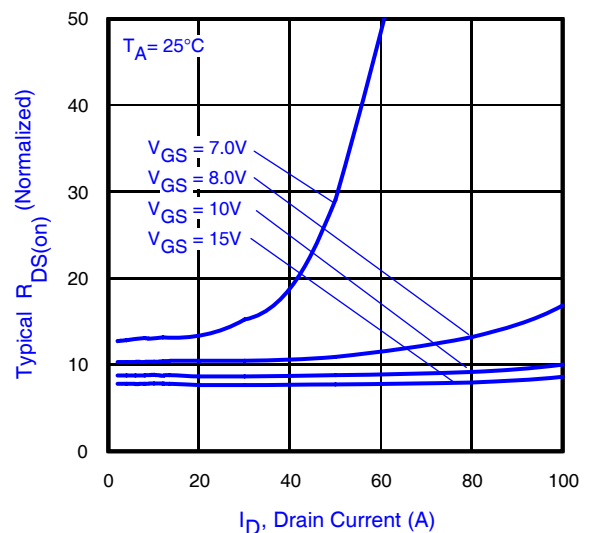
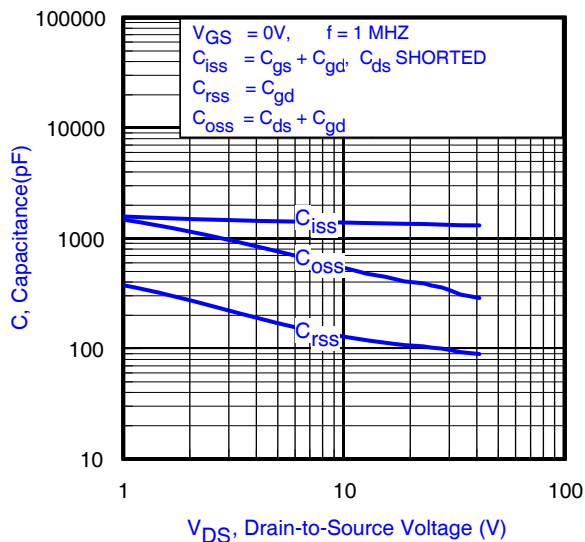
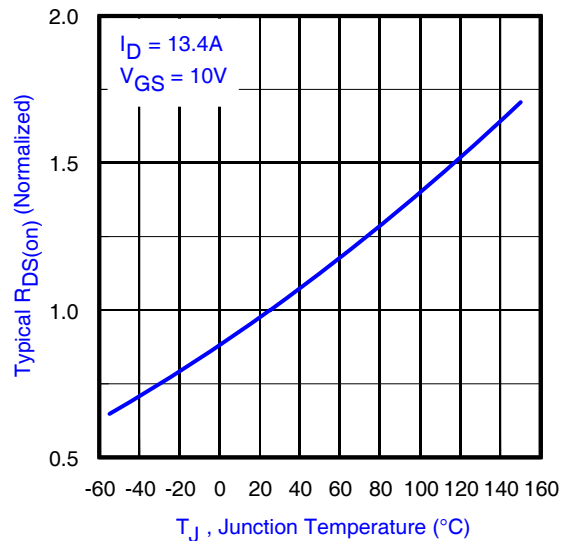
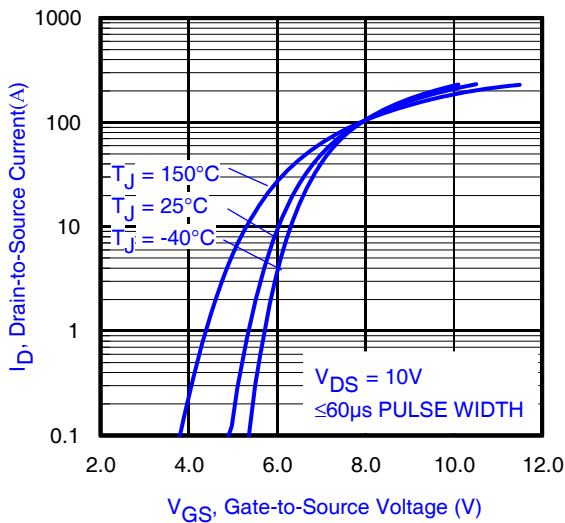
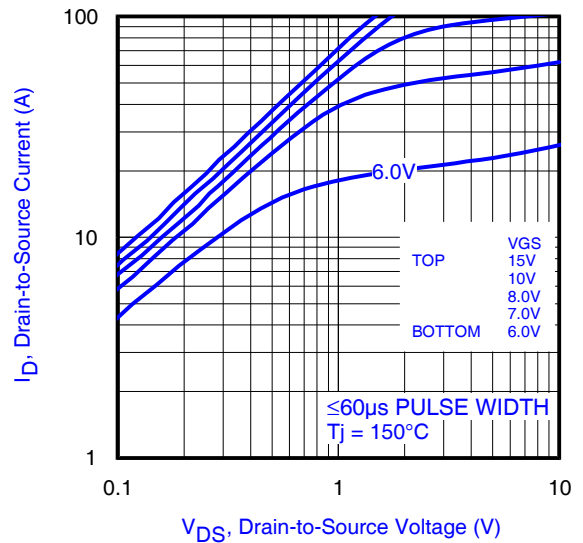
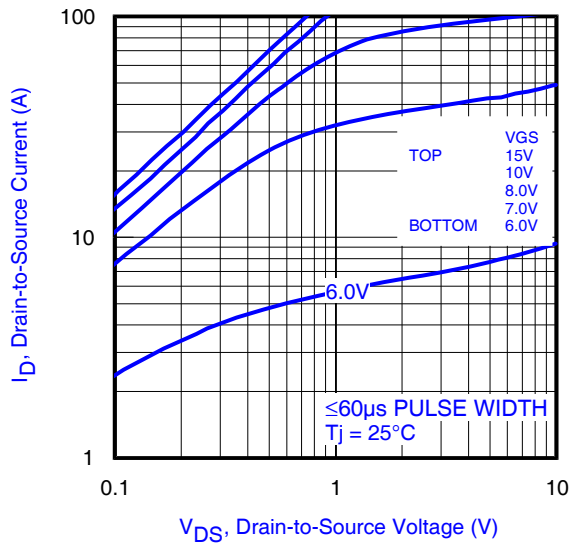
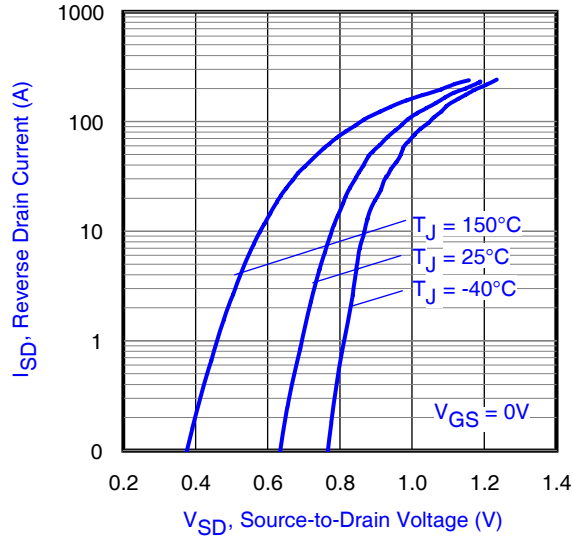
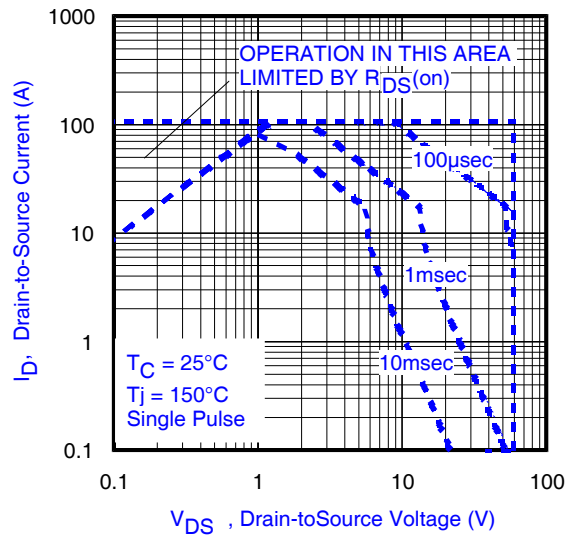


Fig 8. Typical Capacitance vs. Drain-to-Source Voltage

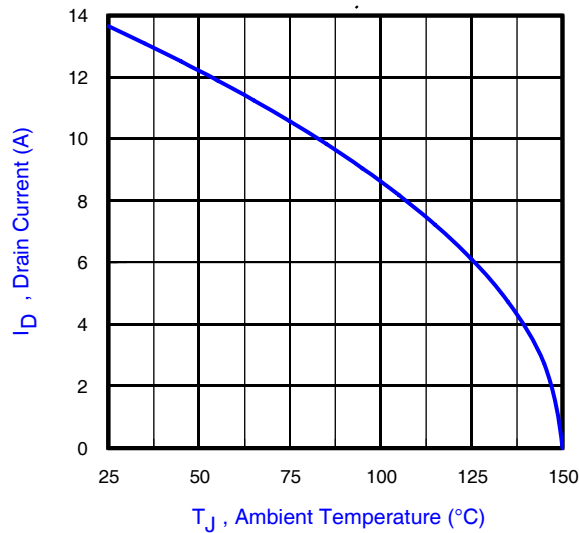
Fig 9. Typical On-Resistance vs. Drain Current



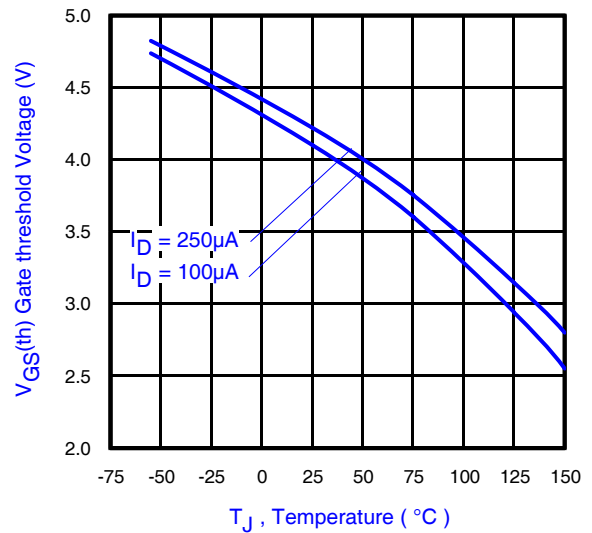
**Fig 10.** Typical Source-Drain Diode Forward Voltage



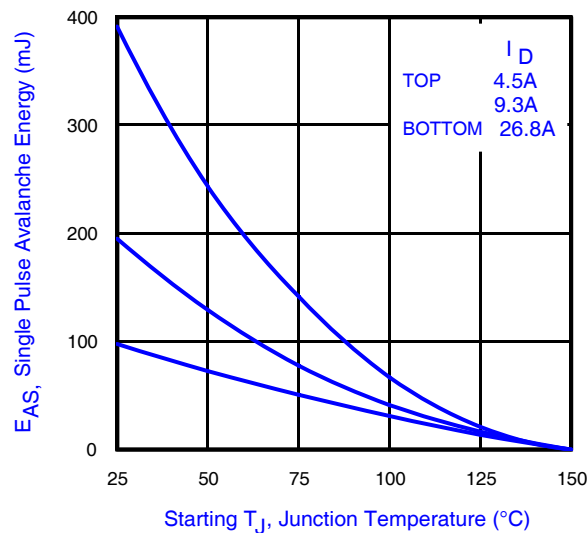
**Fig11.** Maximum Safe Operating Area



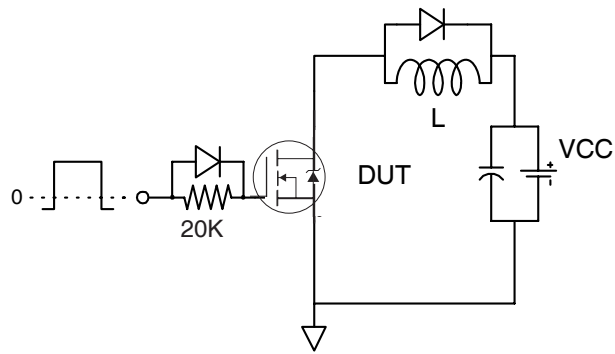
**Fig 12.** Maximum Drain Current vs. Ambient Temperature



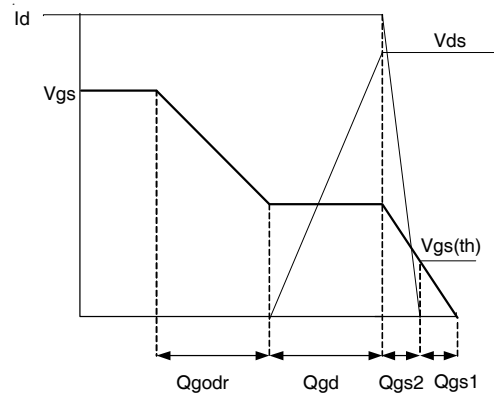
**Fig 13.** Typical Threshold Voltage vs. Junction Temperature



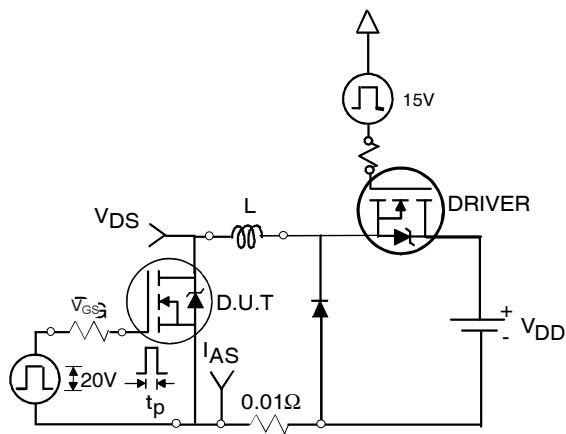
**Fig 14.** Maximum Avalanche Energy vs. Drain Current



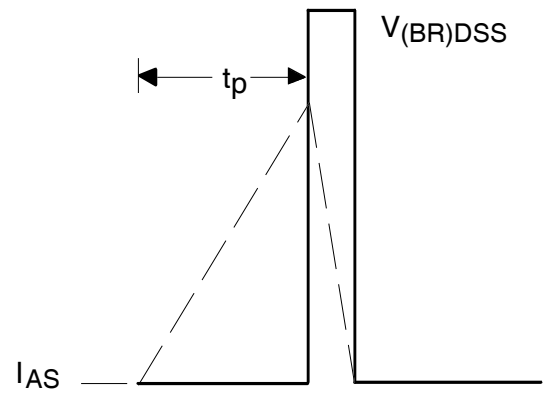
**Fig 15a.** Gate Charge Test Circuit



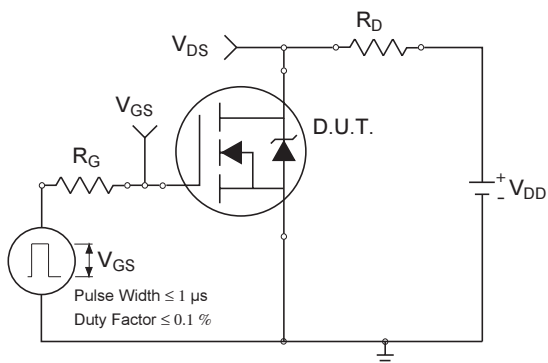
**Fig 15b.** Gate Charge Waveform



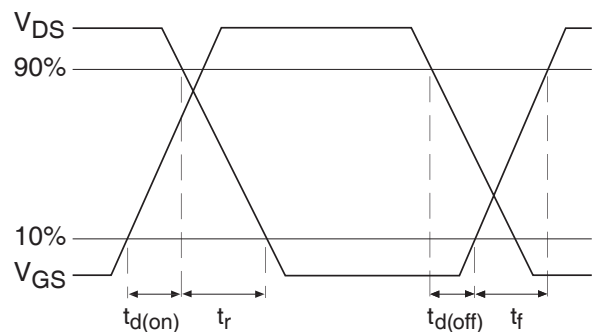
**Fig 16a.** Unclamped Inductive Test Circuit



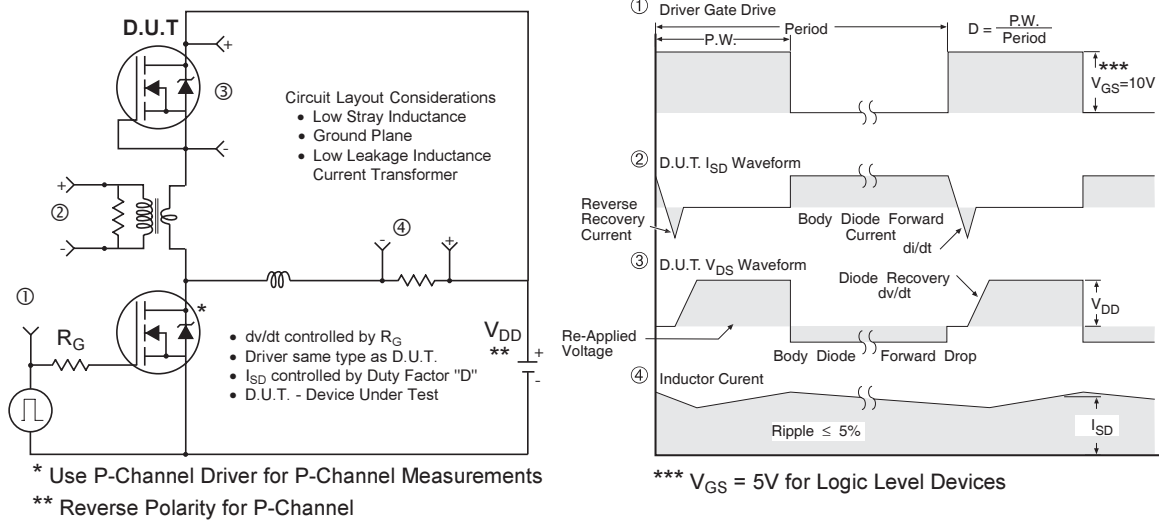
**Fig 16b.** Unclamped Inductive Waveforms



**Fig 17a.** Switching Time Test Circuit



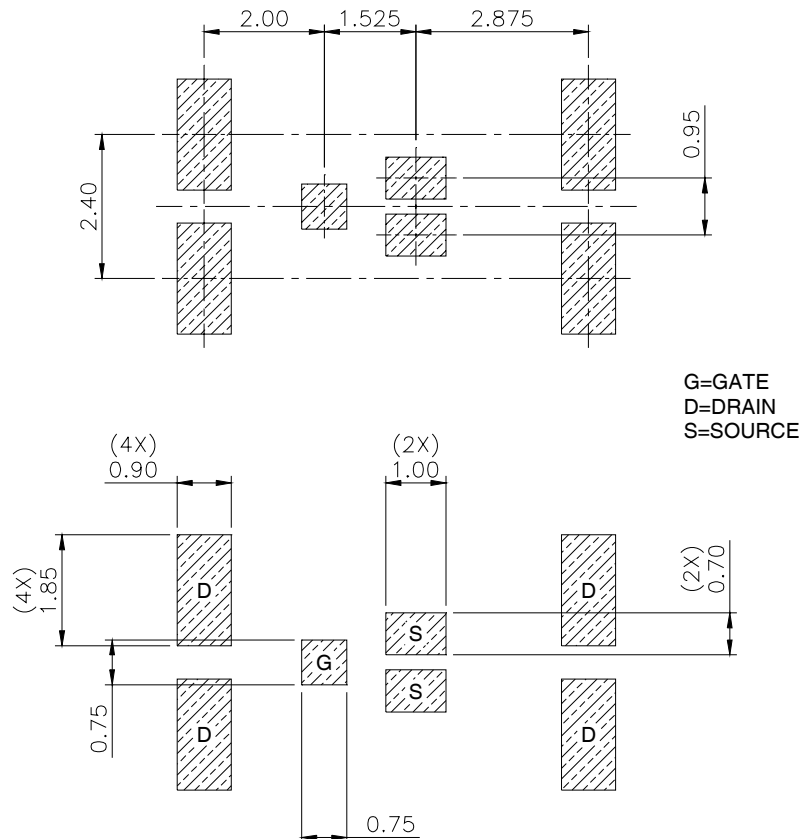
**Fig 17b.** Switching Time Waveforms



**Fig 18.** Diode Reverse Recovery Test Circuit for HEXFET® Power MOSFETs

### DirectFET™ Substrate and PCB Layout, MZ Outline (Medium Size Can, Z-Designation).

Please see AN-1035 for DirectFET assembly details and stencil and substrate design recommendations



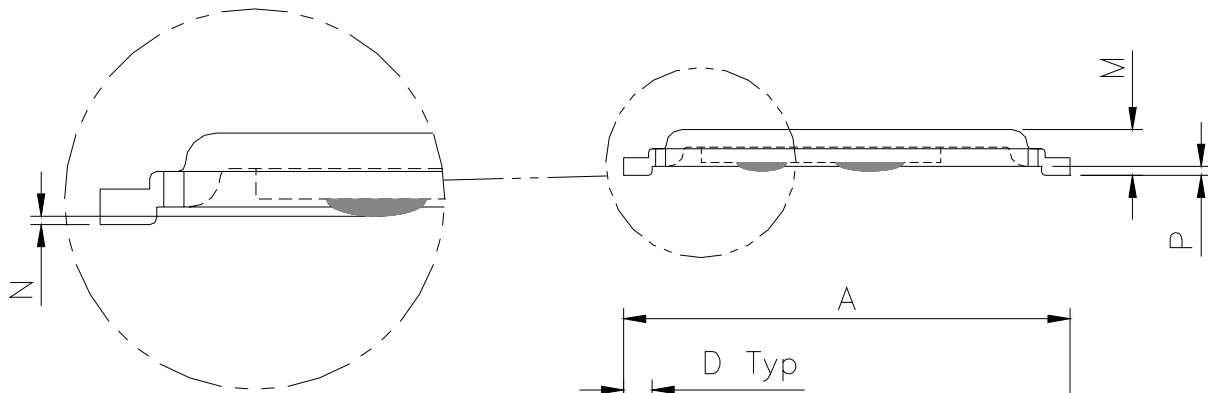
Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>  
www.irf.com



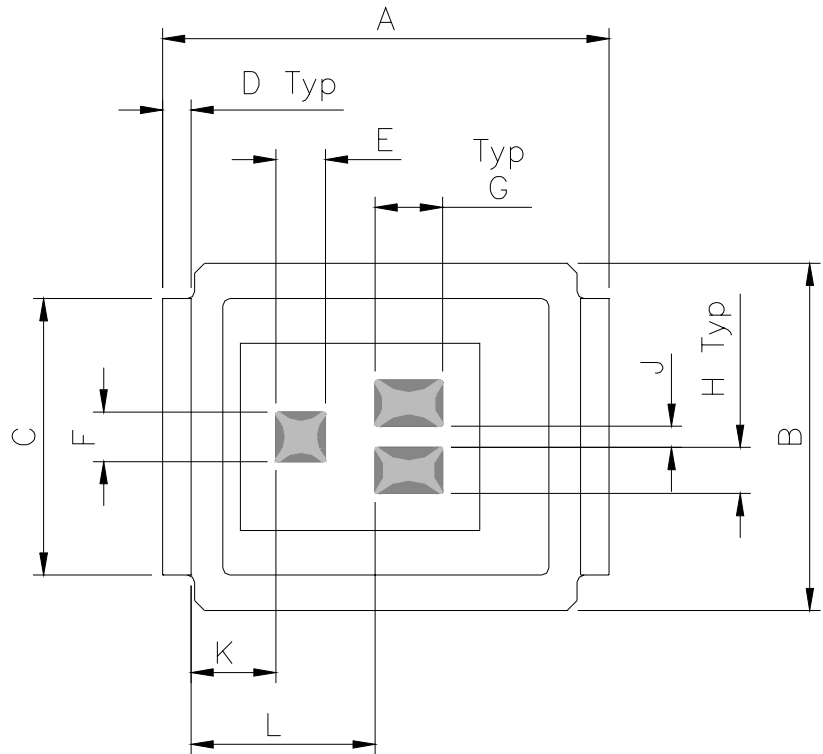
# IRF6674TRPbF

## DirectFET™ Outline Dimension, MZ Outline (Medium Size Can, Z-Designation).

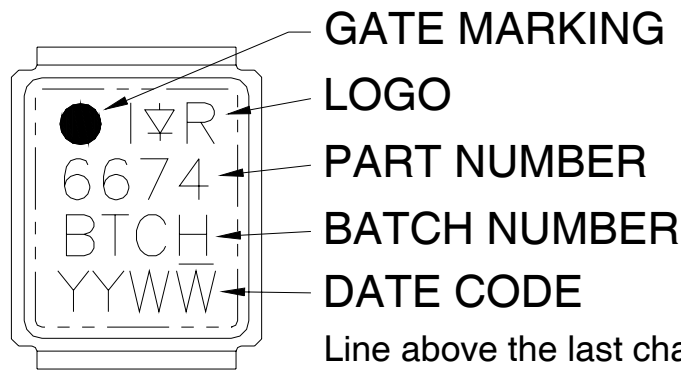
Please see AN-1035 for DirectFET assembly details and stencil and substrate design recommendations



DIMENSIONS				
CODE	METRIC		IMPERIAL	
	MIN	MAX	MIN	MAX
A	6.25	6.35	0.246	0.250
B	4.80	5.05	0.189	0.201
C	3.85	3.95	0.152	0.156
D	0.35	0.45	0.014	0.018
E	0.68	0.72	0.027	0.028
F	0.68	0.72	0.027	0.028
G	0.93	0.97	0.037	0.038
H	0.63	0.67	0.025	0.026
J	0.28	0.32	0.011	0.013
K	1.13	1.26	0.044	0.050
L	2.53	2.66	0.100	0.105
M	0.59	0.70	0.023	0.028
N	0.03	0.08	0.001	0.003
P	0.08	0.17	0.003	0.007



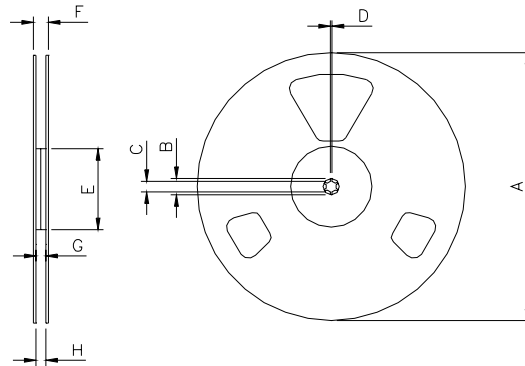
## DirectFET™ Part Marking



Line above the last character of the date code indicates "Lead-Free"

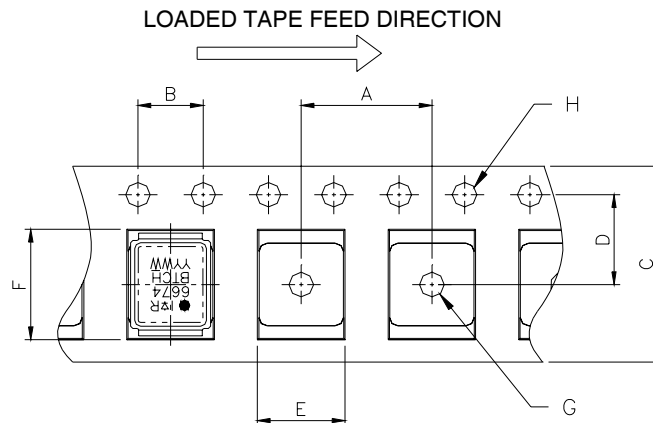
Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>

## DirectFET™ Tape & Reel Dimension (Showing component orientation).



NOTE: Controlling dimensions in mm  
 Std reel quantity is 4800 parts. (ordered as IRF6674MTRPbF). For 1000 parts on 7" reel, order IRF6674MTR1PbF

REEL DIMENSIONS								
CODE	STANDARD OPTION (QTY 4800)				TR1 OPTION (QTY 1000)			
	METRIC		IMPERIAL		METRIC		IMPERIAL	
	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
A	330.0	N.C	12.992	N.C	177.77	N.C	6.9	N.C
B	20.2	N.C	0.795	N.C	19.06	N.C	0.75	N.C
C	12.8	13.2	0.504	0.520	13.5	12.8	0.53	0.50
D	1.5	N.C	0.059	N.C	1.5	N.C	0.059	N.C
E	100.0	N.C	3.937	N.C	58.72	N.C	2.31	N.C
F	N.C	18.4	N.C	0.724	N.C	13.50	N.C	0.53
G	12.4	14.4	0.488	0.567	11.9	12.01	0.47	N.C
H	11.9	15.4	0.469	0.606	11.9	12.01	0.47	N.C



NOTE: CONTROLLING DIMENSIONS IN MM

DIMENSIONS				
CODE	METRIC		IMPERIAL	
	MIN	MAX	MIN	MAX
A	7.90	8.10	0.311	0.319
B	3.90	4.10	0.154	0.161
C	11.90	12.30	0.469	0.484
D	5.45	5.55	0.215	0.219
E	5.10	5.30	0.201	0.209
F	6.50	6.70	0.256	0.264
G	1.50	N.C	0.059	N.C
H	1.50	1.60	0.059	0.063

Data and specifications subject to change without notice.  
 This product has been designed and qualified for the Consumer market.  
 Qualification Standards can be found on IR's Web site.